

## 16-Bit Buffers/Line Drivers

### Features

- Low power, pin-compatible replacement for LCX and LPT families
- 5V tolerant inputs and outputs
- 24 mA balanced drive outputs
- Power-off disable outputs permits live insertion
- Edge-rate control circuitry for reduced noise
- FCT-C speed at 4.1 ns
- Latch-up performance exceeds JEDEC standard no. 17
- Typical output skew < 250 ps
- Industrial temperature range of  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$
- TSSOP (19.6-mil pitch) or SSOP (25-mil pitch)
- Typical  $V_{Olp}$  (ground bounce) performance exceeds Mil Std 883D
- $V_{CC} = 2.7\text{V}$  to  $3.6\text{V}$
- ESD (HBM) > 2000V

### CY74FCT163H244

- Bus hold on data inputs
- Eliminates the need for external pull-up or pull-down resistors
- Devices with bus hold are not recommended for translating rail-to-rail CMOS signals to 3.3V logic levels

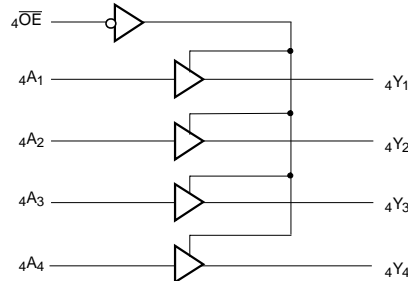
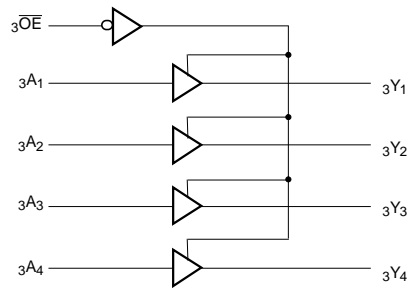
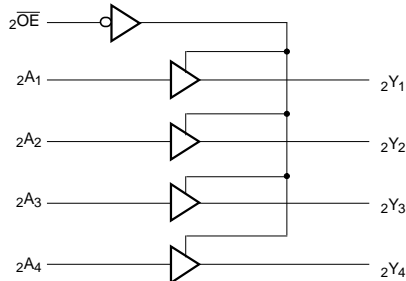
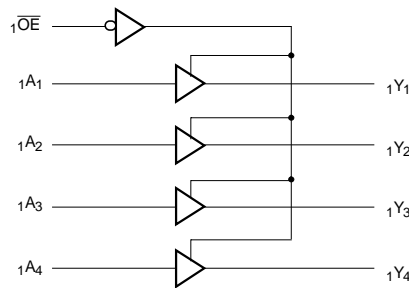
### Functional Description

These 16-bit buffers/line drivers are designed for use in memory driver, clock driver, or other bus interface applications, where high-speed and low power are required. The three-state controls are designed to allow 4-bit, 8-bit or combined 16-bit operation. Flow-through pinout and small shrink packaging simplifies board layout.

The CY74FCT163244 has 24-mA balanced output drivers with current limiting resistors in the outputs.

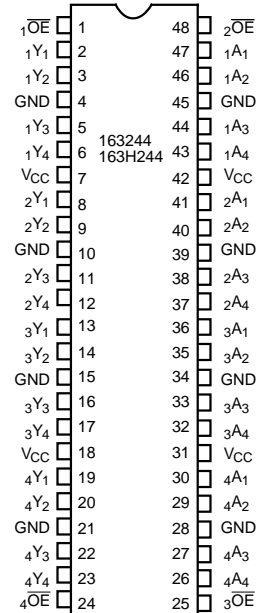
The CY74FCT163H244 has "bus hold" on the data inputs, which retains the last state of the input whenever the source driving the input goes to high impedance. This eliminates the need for pull-up/down resistors and prevents floating inputs.

### Logic Block Diagrams CY74FCT163244, CY74FCT163H244



### Pin Configuration

#### SSOP/TSSOP Top View



**Pin Description**

Name	Description
$\overline{OE}$	Three-State Output Enable Inputs (Active LOW)
A	Data Inputs <sup>[1]</sup>
Y	Three-State Outputs

**Function Table<sup>[2]</sup>**

Inputs		Outputs
$\overline{OE}$	A	Y
L	L	L
L	H	H
H	X	Z

**Maximum Ratings<sup>[3,4]</sup>**

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature.....	-55°C to +125°C
Ambient Temperature with Power Applied.....	-55°C to +125°C
Supply Voltage Range .....	0.5V to +4.6V
DC Input Voltage .....	-0.5V to +7.0V
DC Output Voltage.....	-0.5V to +7.0V
DC Output Current (Maximum Sink Current/Pin) .....	-60 to +120 mA
Power Dissipation .....	1.0W

**Operating Range**

Range	Ambient Temperature	V <sub>CC</sub>
Industrial	-40°C to +85°C	2.7V to 3.6V

**Electrical Characteristics for Non Bus Hold Devices** Over the Operating Range V<sub>CC</sub>=2.7V to 3.6V

Parameter	Description	Test Conditions	Min.	Typ. <sup>[5]</sup>	Max.	Unit
V <sub>IH</sub>	Input HIGH Voltage	All Inputs	2.0		5.5	V
V <sub>IL</sub>	Input LOW Voltage				0.8	V
V <sub>H</sub>	Input Hysteresis <sup>[6]</sup>			100		mV
V <sub>IK</sub>	Input Clamp Diode Voltage	V <sub>CC</sub> =Min., I <sub>IN</sub> =-18 mA		-0.7	-1.2	V
I <sub>IH</sub>	Input HIGH Current	V <sub>CC</sub> =Max., V <sub>I</sub> =5.5			±1	µA
I <sub>IL</sub>	Input LOW Current	V <sub>CC</sub> =Max., V <sub>I</sub> =GND			±1	µA
I <sub>OZH</sub>	High Impedance Output Current (Three-State Output pins)	V <sub>CC</sub> =Max., V <sub>OUT</sub> =5.5V			±1	µA
I <sub>OZL</sub>	High Impedance Output Current (Three-State Output pins)	V <sub>CC</sub> =Max., V <sub>OUT</sub> =GND			±1	µA
I <sub>OS</sub>	Short Circuit Current <sup>[7]</sup>	V <sub>CC</sub> =Max., V <sub>OUT</sub> =GND	-60	-135	-240	mA
I <sub>OFF</sub>	Power-Off Disable	V <sub>CC</sub> =0V, V <sub>OUT</sub> ≤4.5V			±100	µA
I <sub>CC</sub>	Quiescent Power Supply Current	V <sub>IN</sub> ≤0.2V, V <sub>IN</sub> ≥V <sub>CC</sub> -0.2V, V <sub>CC</sub> =Max.		0.1	10	µA
ΔI <sub>CC</sub>	Quiescent Power Supply Current (TTL inputs HIGH)	V <sub>IN</sub> =V <sub>CC</sub> -0.6V <sup>[8]</sup> , V <sub>CC</sub> =Max.		2.0	30	µA

**Notes:**

- On the CY74FCT163H244, these pins have "bus hold."
- H = HIGH Voltage Level. L = LOW Voltage Level. X = Don't Care. Z = High Impedance.
- Operation beyond the limits set forth may impair the useful life of the device. Unless otherwise noted, these limits are over the operating free-air temperature range.
- With the exception of inputs with bus hold, unused inputs must always be connected to an appropriate logic voltage level, preferably either V<sub>CC</sub> or ground.
- Typical values are at V<sub>CC</sub>=3.3V, T<sub>A</sub> = +25°C ambient.
- This parameter is specified but not tested.
- Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parametric tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.
- Per TTL driven input; all other inputs at V<sub>CC</sub> or GND.

**Electrical Characteristics For Bus Hold Devices** Over the Operating Range  $V_{CC}=2.7V$  to  $3.6V$ 

Parameter	Description	Test Conditions	Min.	Typ. <sup>[5]</sup>	Max.	Unit
$V_{IH}$	Input HIGH Voltage	All Inputs	2.0		$V_{CC}$	V
$V_{IL}$	Input LOW Voltage				0.8	V
$V_H$	Input Hysteresis <sup>[6]</sup>			100		mV
$V_{IK}$	Input Clamp Diode Voltage	$V_{CC}=\text{Min.}, I_{IN}=-18\text{ mA}$		-0.7	-1.2	V
$I_{IH}$	Input HIGH Current	$V_{CC}=\text{Max.}, V_I=V_{CC}$			$\pm 100$	$\mu\text{A}$
$I_{IL}$	Input LOW Current				$\pm 100$	$\mu\text{A}$
$I_{BBH}$ $I_{BBL}$	Bus Hold Sustain Current on Bus Hold Input <sup>[9]</sup>	$V_{CC}=\text{Min.}$ $V_I=2.0V$	-50			$\mu\text{A}$
		$V_I=0.8V$	+50			$\mu\text{A}$
$I_{BHHO}$ $I_{BHLO}$	Bus Hold Overdrive Current on Bus Hold Input <sup>[9]</sup>	$V_{CC}=\text{Max.}, V_I=1.5V$			$\pm 500$	$\mu\text{A}$
$I_{OZH}$	High Impedance Output Current (Three-State Output pins)	$V_{CC}=\text{Max.}, V_{OUT}=V_{CC}$			$\pm 1$	$\mu\text{A}$
$I_{OZL}$	High Impedance Output Current (Three-State Output pins)	$V_{CC}=\text{Max.}, V_{OUT}=\text{GND}$			$\pm 1$	$\mu\text{A}$
$I_{OS}$	Short Circuit Current <sup>[7]</sup>	$V_{CC}=\text{Max.}, V_{OUT}=\text{GND}$	-60	-135	-240	mA
$I_{OFF}$	Power-Off Disable	$V_{CC}=0V, V_{OUT}\leq 4.5V$			$\pm 100$	$\mu\text{A}$
$I_{CC}$	Quiescent Power Supply Current	$V_{IN}\leq 0.2V,$ $V_{IN}\geq V_{CC}-0.2V$ $V_{CC}=\text{Max.}$			+40	$\mu\text{A}$
$\Delta I_{CC}$	Quiescent Power supply Current (TTL inputs HIGH)	$V_{IN}=V_{CC}-0.6V$ <sup>[8]</sup> $V_{CC}=\text{Max.}$			+350	$\mu\text{A}$

**Electrical Characteristics For Balanced Drive Devices** Over the Operating Range  $V_{CC}=2.7V$  to  $3.6V$ 

Parameter	Description	Test Conditions	Min.	Typ. <sup>[5]</sup>	Max.	Unit
$I_{ODL}$	Output LOW Dynamic Current <sup>[7]</sup>	$V_{CC}=3.3V, V_{IN}=V_{IH}$ or $V_{IL}, V_{OUT}=1.5V$	45		180	mA
$I_{ODH}$	Output HIGH Dynamic Current <sup>[7]</sup>	$V_{CC}=3.3V, V_{IN}=V_{IH}$ or $V_{IL}, V_{OUT}=1.5V$	-45		-180	mA
$V_{OH}$	Output HIGH Voltage	$V_{CC}=\text{Min.}, I_{OH}=-0.1\text{ mA}$	$V_{CC}-0.2$			V
		$V_{CC}=3.0V, I_{OH}=-8\text{ mA}$	2.4 <sup>[10]</sup>	3.0		V
		$V_{CC}=3.0V, I_{OH}=-24\text{ mA}$	2.0	3.0		V
$V_{OL}$	Output LOW Voltage	$V_{CC}=\text{Min.}, I_{OL}=0.1\text{ mA}$			0.2	V
		$V_{CC}=\text{Min.}, I_{OL}=24\text{ mA}$		0.3	0.55	V

**Notes:**

9. Pins with bus hold are described in Pin Description.  
10.  $V_{OH} = V_{CC} - 0.6V$  at rated current.

**Capacitance<sup>[6]</sup>** ( $T_A = +25^\circ\text{C}$ ,  $f = 1.0\text{ MHz}$ )

Parameter	Description	Test Conditions	Typ. <sup>[5]</sup>	Max.	Unit
$C_{IN}$	Input Capacitance	$V_{IN} = 0V$	4.5	6.0	pF
$C_{OUT}$	Output Capacitance	$V_{OUT} = 0V$	5.5	8.0	pF

**Power Supply Characteristics**

Parameter	Description	Test Conditions	Typ. <sup>[5]</sup>	Max.	Unit	
$I_{CCD}$	Dynamic Power Supply Current <sup>[10]</sup>	$V_{CC} = \text{Max.}$ , One Input Toggling, 50% Duty Cycle, Outputs Open, $\overline{OE} = \text{GND}$	50	75	$\mu\text{A}/\text{MHz}$	
$I_C$	Total Power Supply Current <sup>[11]</sup>	$V_{CC} = \text{Max.}$ , $f_1 = 10\text{ MHz}$ , 50% Duty Cycle, Outputs Open, One Bit Toggling, $\overline{OE} = \text{GND}$	$V_{IN} = V_{CC}$ or $V_{IN} = \text{GND}$	0.5	0.8	mA
			$V_{IN} = V_{CC} - 0.6V$ or $V_{IN} = \text{GND}$	0.5	0.8	mA
		$V_{CC} = \text{Max.}$ , $f_1 = 2.5\text{ MHz}$ , 50% Duty Cycle, Outputs Open, Sixteen Bits Toggling, $\overline{OE} = \text{GND}$	$V_{IN} = V_{CC}$ or $V_{IN} = \text{GND}$	2.0	3.0 <sup>[12]</sup>	mA
			$V_{IN} = V_{CC} - 0.6V$ or $V_{IN} = \text{GND}$	2.0	3.3 <sup>[12]</sup>	mA

**Notes:**

11. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
12.  $I_C = I_{\text{QUIESCENT}} + I_{\text{INPUTS}} + I_{\text{DYNAMIC}}$   
 $I_C = I_{CC} + \Delta I_{CC} D_H N_T + I_{CCD} (f_0/2 + f_1 N_1)$   
 $I_{CC} =$  Quiescent Current with CMOS input levels  
 $\Delta I_{CC} =$  Power Supply Current for a TTL HIGH input ( $V_{IN} = 3.4V$ )  
 $D_H =$  Duty Cycle for TTL inputs HIGH  
 $N_T =$  Number of TTL inputs at  $D_H$   
 $I_{CCD} =$  Dynamic Current caused by an input transition pair (HLH or LHL)  
 $f_0 =$  Clock frequency for registered devices, otherwise zero  
 $f_1 =$  Input signal frequency  
 $N_1 =$  Number of inputs changing at  $f_1$   
 All currents are in milliamps and all frequencies are in megahertz.
13. Values for these conditions are examples of the  $I_{CC}$  formula. These limits are specified but not tested.

**Switching Characteristics Over the Operating Range  $V_{CC}=3.0V$  to  $3.6V$ <sup>[14,15]</sup>**

Parameter	Description	CY74FCT163244A CY74FCT163H244A		CY74FCT163244C CY74FCT163H244C		Unit	Fig. No. <sup>[16]</sup>
		Min.	Max.	Min.	Max.		
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay Data to Output	1.5	4.8	1.5	4.1	ns	1, 3
t <sub>PZH</sub> t <sub>PZL</sub>	Output Enable Time	1.5	6.2	1.5	5.8	ns	1, 7, 8
t <sub>PHZ</sub> t <sub>PLZ</sub>	Output Disable Time	1.5	5.6	1.5	5.2	ns	1, 7, 8
t <sub>SK(O)</sub>	Output Skew <sup>[17]</sup>		0.5		0.5	ns	—

**Notes:**

14. Minimum limits are specified but not tested on Propagation Delays.  
15. For  $V_{CC}=2.7$ , propagation delay, output enable and output disable times should be degraded by 20%.  
16. See "Parameter Measurement Information" in the General Information section.  
17. Skew between any two outputs of the same package switching in the same direction. This parameter is ensured by design.

**Ordering Information CY74FCT163244**

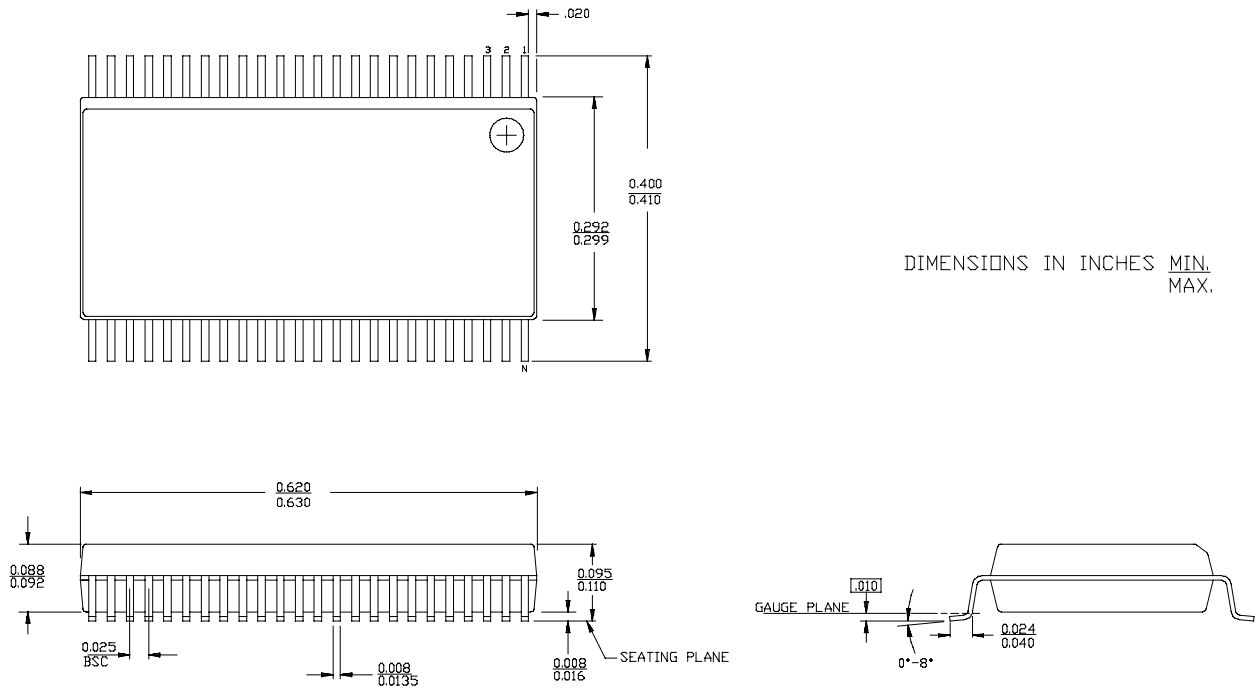
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
4.1	CY74FCT163244CPACT	Z48	48-Lead (240-Mil) TSSOP	Industrial
	CY74FCT163244CPVC/PVCT	O48	48-Lead (300-Mil) SSOP	
4.8	CY74FCT163244APACT	Z48	48-Lead (240-Mil) TSSOP	Industrial
	CY74FCT163244APVC/PVCT	O48	48-Lead (300-Mil) SSOP	

**Ordering Information CY74FCT163H244**

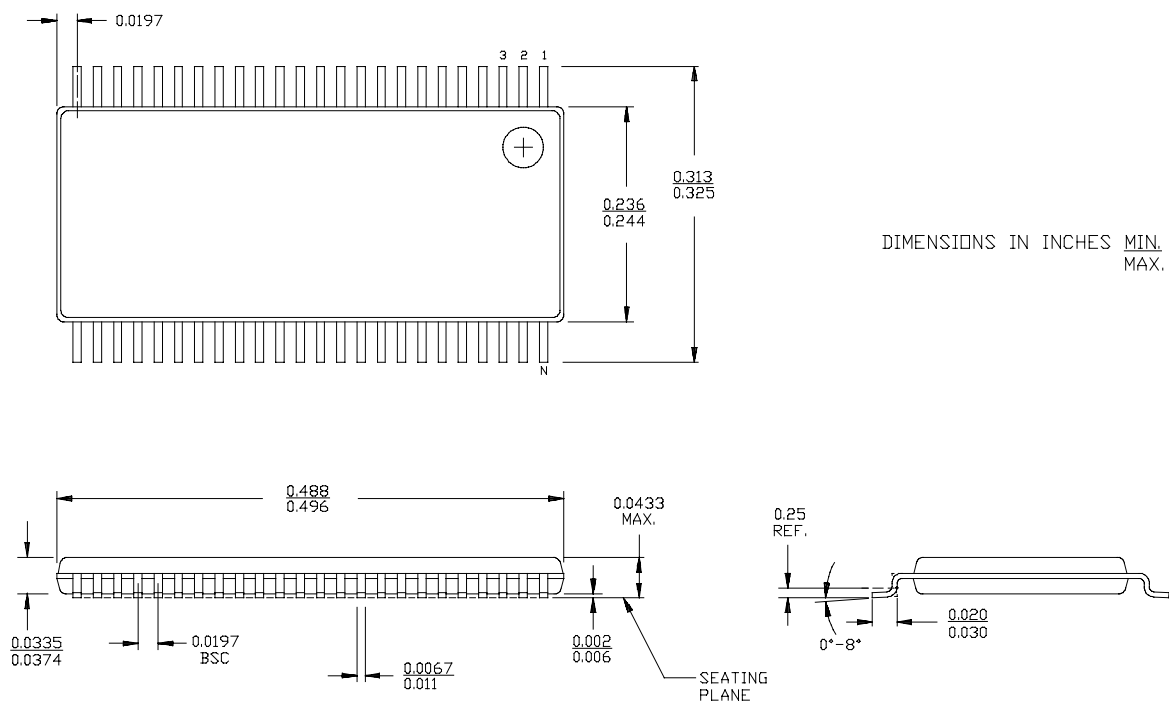
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
4.1	74FCT163H244CPACT	Z48	48-Lead (240-Mil) TSSOP	Industrial
	CY74FCT163H244CPVC	O48	48-Lead (300-Mil) SSOP	
	74FCT163H244CPVCT	O48	48-Lead (300-Mil) SSOP	

**Package Diagrams**

**48-Lead Shrunken Small Outline Package O48**



**48-Lead Thin Shrunken Small Outline Package Z48**



**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74FCT163H244CPACT	OBSOLETE	TSSOP	DGG	48		TBD	Call TI	Call TI
74FCT163H244CPVCT	OBSOLETE	SSOP	DL	48		TBD	Call TI	Call TI
CY74FCT163244APAC	OBSOLETE	TSSOP	DGG	48		TBD	Call TI	Call TI
CY74FCT163244APACT	OBSOLETE	TSSOP	DGG	48		TBD	Call TI	Call TI
CY74FCT163244APVC	OBSOLETE	SSOP	DL	48		TBD	Call TI	Call TI
CY74FCT163244APVCT	OBSOLETE	SSOP	DL	48		TBD	Call TI	Call TI
CY74FCT163244CPAC	OBSOLETE	TSSOP	DGG	48		TBD	Call TI	Call TI
CY74FCT163244CPACT	OBSOLETE	TSSOP	DGG	48		TBD	Call TI	Call TI
CY74FCT163244CPVC	OBSOLETE	SSOP	DL	48		TBD	Call TI	Call TI
CY74FCT163244CPVCT	OBSOLETE	SSOP	DL	48		TBD	Call TI	Call TI
CY74FCT163H244CPAC	OBSOLETE	TSSOP	DGG	48		TBD	Call TI	Call TI
CY74FCT163H244CPVC	OBSOLETE	SSOP	DL	48		TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

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**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

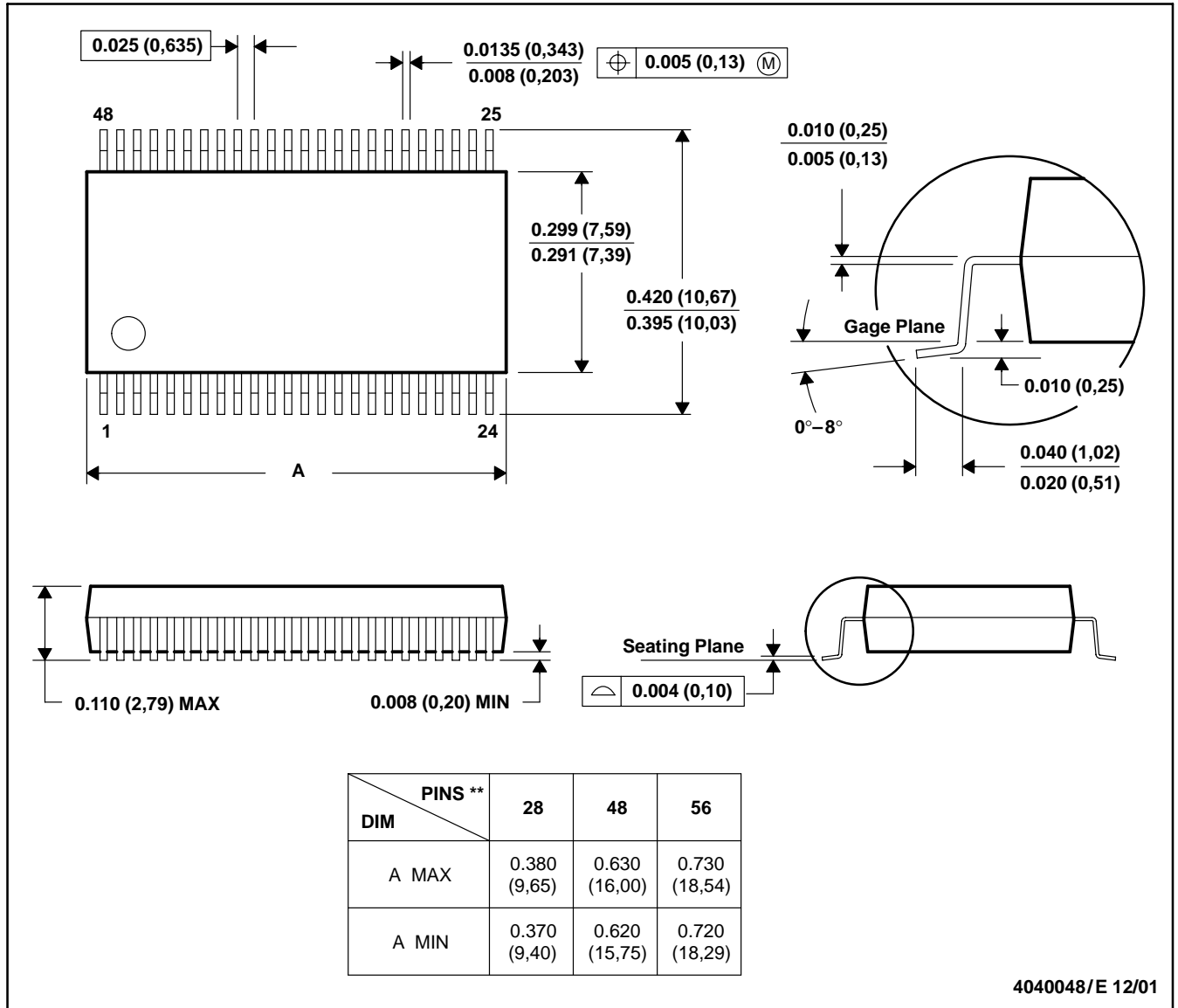
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DL (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).  
 D. Falls within JEDEC MO-118



DGG (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
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 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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